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Moldar	ation Method:
Molded	
	ing Hole Diameter:
0.093 i	
	Mounting Hole Accommodation Diameter:
0.400 i	
	ing Hole Style:
	, w/two mounting holes
-	ic Equipment Accommodated:
Semico	onductor device
Conta	ct Material:
Coppe	r alloy
Accon	nmodated Contact Quantity:
4	
Polariz	zation Type:
Contac	ot position
Mount	ing Method:
Saddle	
Mount	ing Type For Which Designed:
Chassi	is
Termir	nal Type And Quantity:
4 tab,	solder lug
Shelf L	_ife:
N/a	
Unit O	f Measure:
Demili	tarization:
No	
Fiig:	
A0230	0